



Features:

- High power chip LEDs
- 3.5 x 2.8 x 1.9mm Standard directivity
- Superior weather-resistance
- UV resistant epoxy
- RoHS compliant

Applications

- General purpose indicators
- Small area illuminations
- Back lighting

Absolute maximum rating (Ta=25°C)

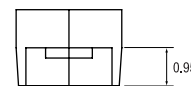
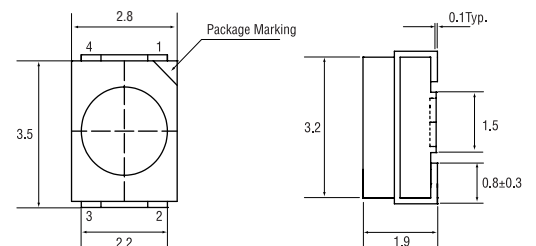
Item	Symbol	Value	Unit
DC Forward current	I_F	30	mA
Pulse forward current*	I_{FP}	100	mA
Reverse voltage	V_R	5	V
Power dissipation	P_D	120	mW
Operating temperature	T_{opr}	-30 to +80	°C
Storage temperature	T_{stg}	-30 to +100	°C
Lead soldering temperature	T_{sol}	260°C/3 sec	-

* Pulse width max. 10ms. Duty ratio max. 1/10

Electrical - Optical characteristics (Ta=25°C)

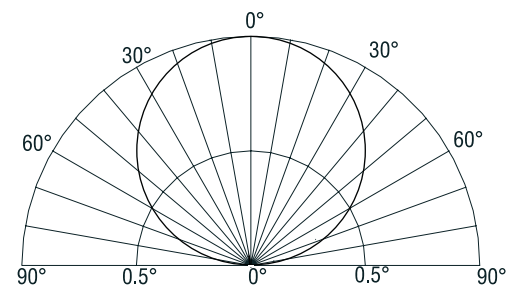
Item	Symbol	Condition	Min.	Typ.	Max.	Unit
DC Forward voltage	V_F (R)	$I_F=20mA$	1.8	2.0	2.4	V
	V_F (B/G)	$I_F=20mA$	2.8	3.2	4.0	V
DC Reverse current	I_R	$V_R=5V$	-	-	10	μA
Dominant wavelength	λ_D (Red)	$I_F=20mA$	620	625	630	nm
	λ_D (Green)	$I_F=20mA$	520	525	530	nm
	λ_D (Blue)	$I_F=20mA$	465	470	475	nm
Luminous intensity	I_v (Red)	$I_F=20mA$	220	330	500	mcd
	I_v (Green)	$I_F=20mA$	220	330	500	mcd
	I_v (Blue)	$I_F=20mA$	150	220	330	mcd

Outline dimensions:



1 Cathode for red
2 Common anode
3 Cathode for blue
4 Cathode for green

Directivity:



Soldering heat reliability (DIP):

IR Reflow soldering profile:

- Reflow soldering should not be done more than two times
- When soldering, do not put stress on the LEDs during heating
- After soldering do not warp the circuit board
- Repairing should not be done after the LEDs have been soldered.

When repairing is unavoidable a double-head soldering iron should be used.
It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing

